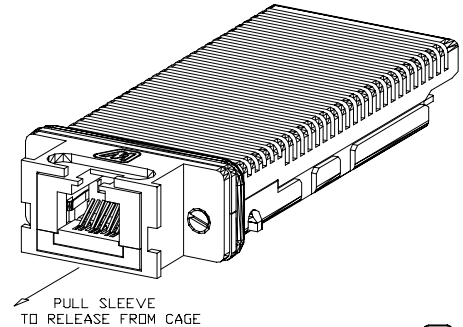
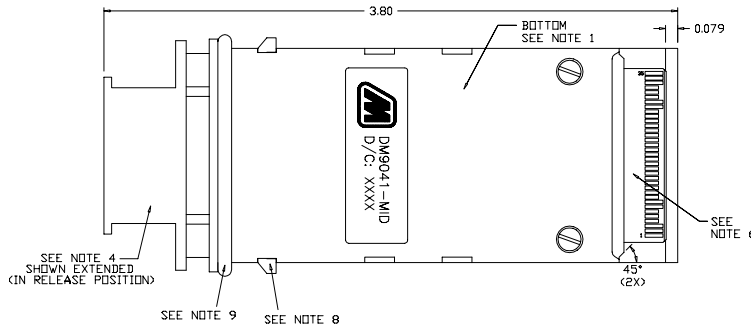
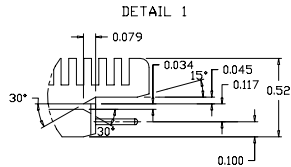
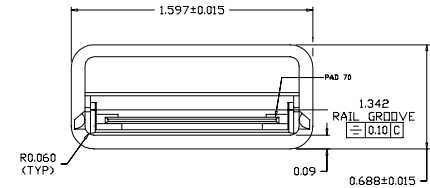
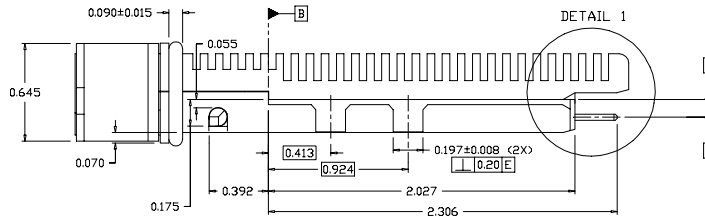
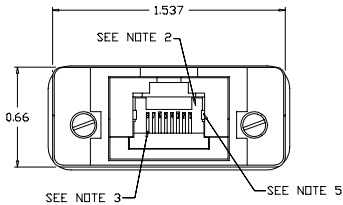
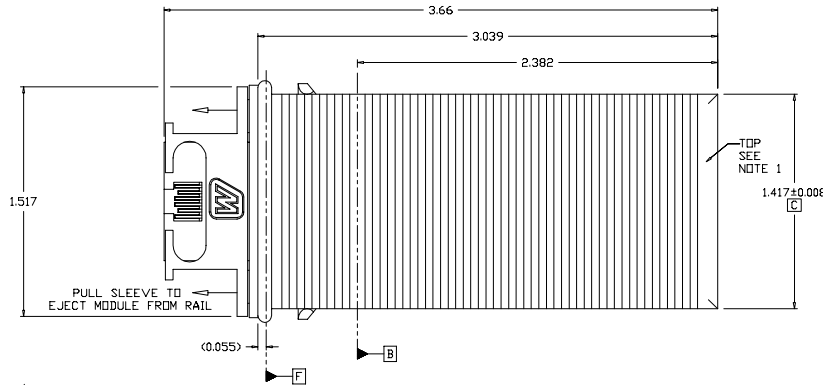


LTR.	ECN	DESCRIPTION	DATE	APP'D.



NOTES:

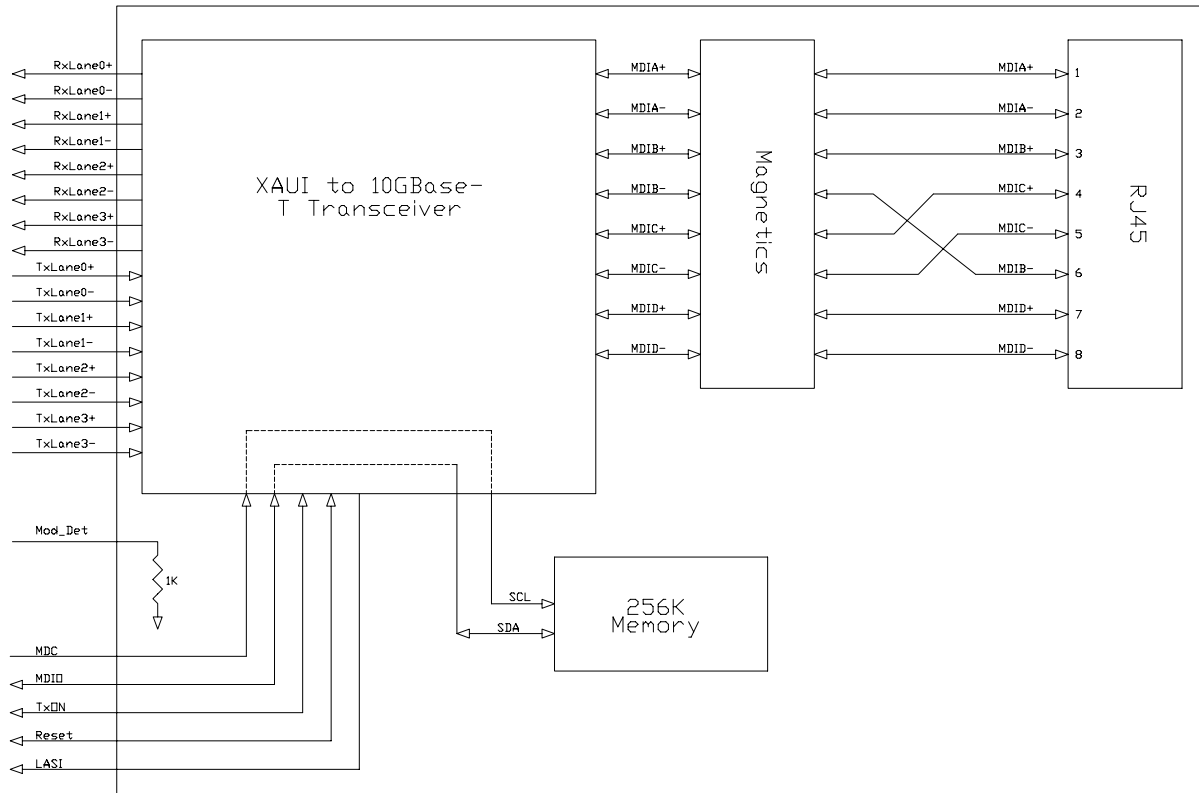
- 1) HOUSING MATERIAL (TOP AND BOTTOM): ZAMAC 3
PLATING: NICKEL OVER COPPER
- 2) RJ45 CONNECTOR - INSULATOR: 30% GLASS FILLED POLYAMIDE; COLOR: BLACK
- 3) RJ45 CONTACTS: PHOSPHOR BRONZE
PLATING: 50µm MIN. HARD GOLD ON CONTACT AREA,
MATTE TIN OVER NICKEL ON SOLDER AREA
- 4) SLEEVE (PULL SLEEVE): ZINC DIE CAST
PLATING: NICKEL OVER COPPER
- 5) GROUNDING TABS: BERYLLIUM COPPER
PLATING: NICKEL
- 6) PCB=039" THICK, 30µm MIN GOLD PLATING OVER
50µm MIN NICKEL ON CONTACT AREA
- 7) SCREWS: STAINLESS STEEL
- 8) LOCK (REVERSE CAM RELEASE): ZAMAC 3
PLATING: NICKEL OVER COPPER
- 9) GASKET: ELECTRICALLY CONDUCTIVE ELASTOMER (SHOWN IN UNCOMPRESSED STATE)

DO NOT SCALE DRAWING.

EXPERIMENTAL NO:		DIVISION ASSIGNED: dataMATE Division	
TOLERANCE UNLESS OTHERWISE SPECIFIED	MATERIAL:	DRAWN BY:	DATE:
METRIC	SEE NOTES	A. PIRILLIS	10/02/07
±	DEC. XX ± .010	CHECKED BY:	
±	XXX ± .005	B. SKEPNEK	10/02/07
±	ANGLES ±	ENGR. APPROVAL:	
TOOLING DWG	FINISH:	J. NOVAK	10/02/07
PART DWG	SEE NOTES	APPROVED BY:	
BREAK SHARP EDGES REMOVE ALL BURRS		A. CHIAPPETTA	10/02/07
THE INFORMATION DISCLOSED IN THIS DOCUMENT IS PROPRIETARY TO METHODE ELECTRONICS, INC. AND MAY NOT BE USED FOR MANUFACTURE OR ANY OTHER PURPOSE WITHOUT THE WRITTEN CONSENT OF METHODE. DRILLS SUBJECT TO CHANGE AS THEY MAY OCCUR WITH RESPECT TO PRODUCT IMPROVEMENT.		PART NO. CLASSIFICATION:	
TITLE: X2 TO RJ45 MODULE WITH PULL SLEEVE MIDPAK VERSION		SIZE: C	CODE IDENT.:
SCALE:		DWG. NUMBER: DM9041-MID	Rev.:
		SHIT. 1 OF 2	

BLOCK DIAGRAM

REVISION AND CHANGE EFFECTIVITY DATE				
LTR.	ECN	DESCRIPTION	DATE	APP'D.



DO NOT SCALE DRAWING.

EXPERIMENTAL NO:		DIVISION ASSIGNED: dataMATE Division	
<small> TOLERANCE UNLESS OTHERWISE SPECIFIED METRIC INCHES ± ± ± ± ± DEC. XX ± .010 XXX ± .005 ANGLES ± TOOLING DWG <input type="checkbox"/> PART DWG <input type="checkbox"/> BREAK SHARP EDGES REMOVE ALL BURRS </small>		MATERIAL: SEE NOTES	DRAWN BY: A. PIRILLIS CHECKED BY: B. SKEPNEK ENGR. APPROVAL: J. NOWAK APPROVED BY: A. CHIAPPETTA DATE: 10/02/07 DATE: 10/02/07 DATE: 10/02/07 DATE: 10/02/07
<small> THE INFORMATION DISCLOSED IN THIS DOCUMENT IS PROPRIETARY TO METHODE ELECTRONICS, INC. AND MAY NOT BE USED FOR MANUFACTURE OR ANY OTHER PURPOSE WITHOUT THE WRITTEN CONSENT OF METHODE. DRILLS SUBJECT TO CHANGE AS THEY MAY CHANGE WITH RESPECT TO PRODUCT IMPROVEMENT. </small>		FINISH: SEE NOTES	TITLE: X2 TO RJ45 MODULE WITH PULL SLEEVE MIDPAK VERSION SIZE: C CODE IDENT.: DWG. NUMBER: DM9041-MID Rev.: SCALE: SHEET: 2 OF 2